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FABRICATION METHOD OF SEMICONDUCTOR DEVICE

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Claim

In a bonding method wherein a pair of semiconductor chips installed with bumps on each surface is connected by orienting each other's bump group, a fabrication method of a semiconductor device characterized by the fact that, while a multiple number of guide bumps are installed around the edge of the bump installation surface of one of the semiconductor chips described previously, a multiple number of connecting bumps are installed around the edge of the bump installation surface of the other corresponding semiconductor chip, and thus with both semiconductor chips being joined in a form wherein each connecting bump of one semiconductor chip is inscribed in each guide bump of other semiconductor chips described previously and facing each other.

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